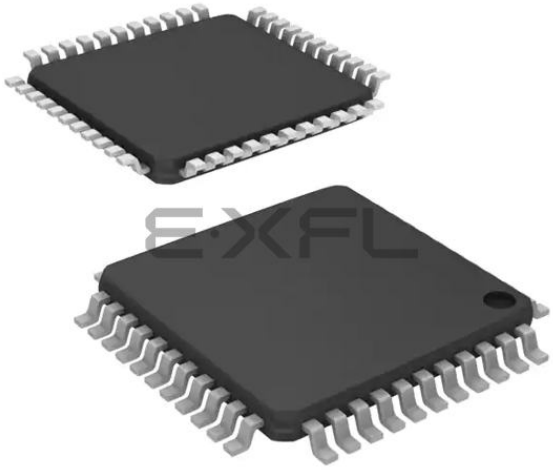
Microchip Technology - PIC16LC74AT-04/PT Datasheet



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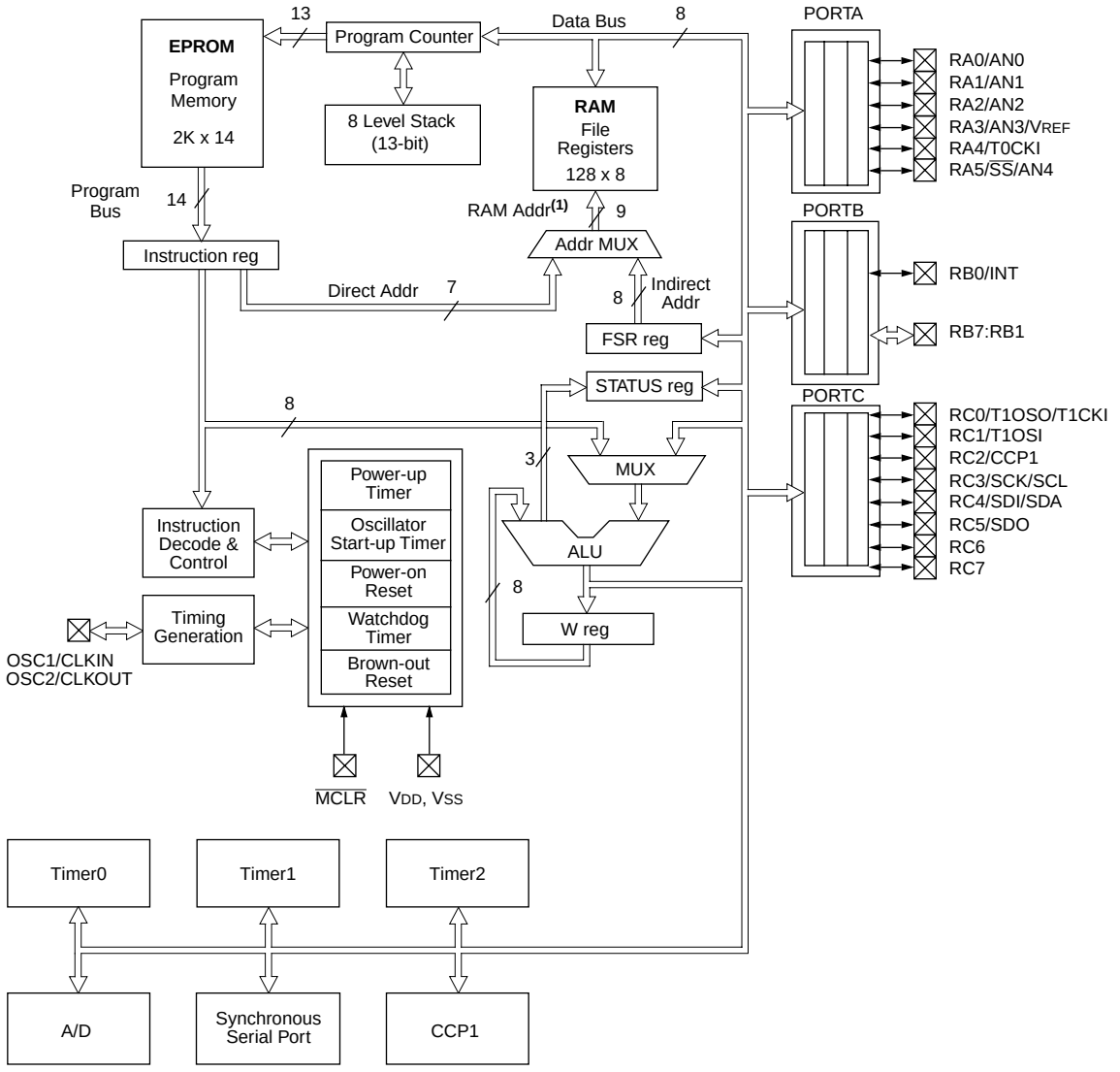
Applications of "Embedded - Microcontrollers"

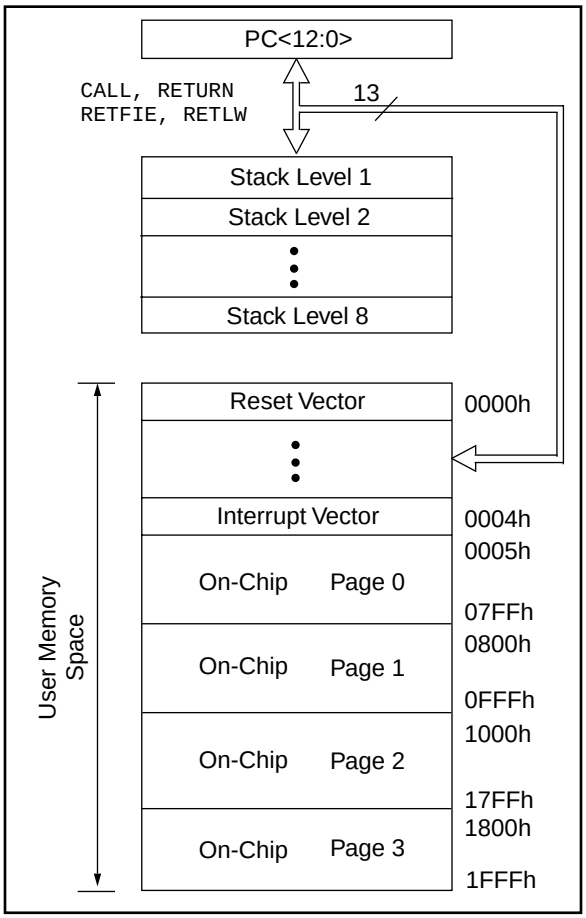
Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc74at-04-pt

FIGURE 3-1: PIC16C72 BLOCK DIAGRAM



Note 1: Higher order bits are from the STATUS register.

FIGURE 4-3: PIC16C76/77 PROGRAM MEMORY MAP AND STACK



4.2 Data Memory Organization

Applicable Devices						
72	73	73A	74	74A	76	77

The data memory is partitioned into multiple banks which contain the General Purpose Registers and the Special Function Registers. Bits RP1 and RP0 are the bank select bits.

RP1:RP0 (STATUS<6:5>)
= 00 → Bank0
= 01 → Bank1
= 10 → Bank2
= 11 → Bank3

Each bank extends up to 7Fh (128 bytes). The lower locations of each bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers, implemented as static RAM. All implemented banks contain special function registers. Some “high use” special function registers from one bank may be mirrored in another bank for code reduction and quicker access.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file can be accessed either directly, or indirectly through the File Select Register FSR (Section 4.5).

TABLE 4-1: PIC16C72 SPECIAL FUNCTION REGISTER SUMMARY (Cont.'d)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets (3)
Bank 1											
80h(1)	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000
81h	OPTION	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h(1)	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
83h(1)	STATUS	IRP(4)	RP1(4)	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu
84h(1)	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111
86h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
88h	—	Unimplemented								—	—
89h	—	Unimplemented								—	—
8Ah(1,2)	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the PC					---0 0000	---0 0000
8Bh(1)	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
8Ch	PIE1	—	ADIE	—	—	SSPIE	CCP1IE	TMR2IE	TMR1IE	-0-- 0000	-0-- 0000
8Dh	—	Unimplemented								—	—
8Eh	PCON	—	—	—	—	—	—	$\overline{POR}$	$\overline{BOR}$	---- --qq	---- --uu
8Fh	—	Unimplemented								—	—
90h	—	Unimplemented								—	—
91h	—	Unimplemented								—	—
92h	PR2	Timer2 Period Register								1111 1111	1111 1111
93h	SSPADD	Synchronous Serial Port (I^2C mode) Address Register								0000 0000	0000 0000
94h	SSPSTAT	—	—	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	--00 0000	--00 0000
95h	—	Unimplemented								—	—
96h	—	Unimplemented								—	—
97h	—	Unimplemented								—	—
98h	—	Unimplemented								—	—
99h	—	Unimplemented								—	—
9Ah	—	Unimplemented								—	—
9Bh	—	Unimplemented								—	—
9Ch	—	Unimplemented								—	—
9Dh	—	Unimplemented								—	—
9Eh	—	Unimplemented								—	—
9Fh	ADCON1	—	—	—	—	—	PCFG2	PCFG1	PCFG0	---- -000	---- -000

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented read as '0'.
Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.
2: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<12:8> whose contents are transferred to the upper byte of the program counter.
3: Other (non power-up) resets include external reset through $\overline{MCLR}$ and Watchdog Timer Reset.
4: The IRP and RP1 bits are reserved on the PIC16C72, always maintain these bits clear.

11.3 SPI Mode for PIC16C76/77

This section contains register definitions and operational characteristics of the SPI module on the PIC16C76 and PIC16C77 only.

FIGURE 11-7: SSPSTAT: SYNC SERIAL PORT STATUS REGISTER (ADDRESS 94h)(PIC16C76/77)

R/W-0	R/W-0	R-0	R-0	R-0	R-0	R-0	R-0
SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n =Value at POR reset

bit 7: **SMP:** SPI data input sample phase
SPI Master Mode
1 = Input data sampled at end of data output time
0 = Input data sampled at middle of data output time
SPI Slave Mode
SMP must be cleared when SPI is used in slave mode

bit 6: **CKE**: SPI Clock Edge Select (Figure 11-11, Figure 11-12, and Figure 11-13)
CKP = 0
1 = Data transmitted on rising edge of SCK
0 = Data transmitted on falling edge of SCK
CKP = 1
1 = Data transmitted on falling edge of SCK
0 = Data transmitted on rising edge of SCK

bit 5: **D/$\overline{A}$**: Data/$\overline{Address}$ bit (I^2C mode only)
1 = Indicates that the last byte received or transmitted was data
0 = Indicates that the last byte received or transmitted was address

bit 4: **P**: Stop bit (I^2C mode only. This bit is cleared when the SSP module is disabled, or when the Start bit is detected last, SSPEN is cleared)
1 = Indicates that a stop bit has been detected last (this bit is '0' on RESET)
0 = Stop bit was not detected last

bit 3: **S**: Start bit (I^2C mode only. This bit is cleared when the SSP module is disabled, or when the Stop bit is detected last, SSPEN is cleared)
1 = Indicates that a start bit has been detected last (this bit is '0' on RESET)
0 = Start bit was not detected last

bit 2: **R/$\overline{W}$**: Read/Write bit information (I^2C mode only)
This bit holds the R/W bit information following the last address match. This bit is only valid from the address match to the next start bit, stop bit, or $\overline{ACK}$ bit.
1 = Read
0 = Write

bit 1: **UA**: Update Address (10-bit I^2C mode only)
1 = Indicates that the user needs to update the address in the SSPADD register
0 = Address does not need to be updated

bit 0: **BF**: Buffer Full Status bit

Receive (SPI and I^2C modes)
1 = Receive complete, SSPBUF is full
0 = Receive not complete, SSPBUF is empty

Transmit (I^2C mode only)
1 = Transmit in progress, SSPBUF is full
0 = Transmit complete, SSPBUF is empty

Figure 11-19 and Figure 11-20 show Master-transmitter and Master-receiver data transfer sequences.

When a master does not wish to relinquish the bus (by generating a STOP condition), a repeated START condition (Sr) must be generated. This condition is identical to the start condition (SDA goes high-to-low while SCL is high), but occurs after a data transfer acknowledge pulse (not the bus-free state). This allows a master to send "commands" to the slave and then receive the requested information or to address a different slave device. This sequence is shown in Figure 11-21.

FIGURE 11-19: MASTER-TRANSMITTER SEQUENCE

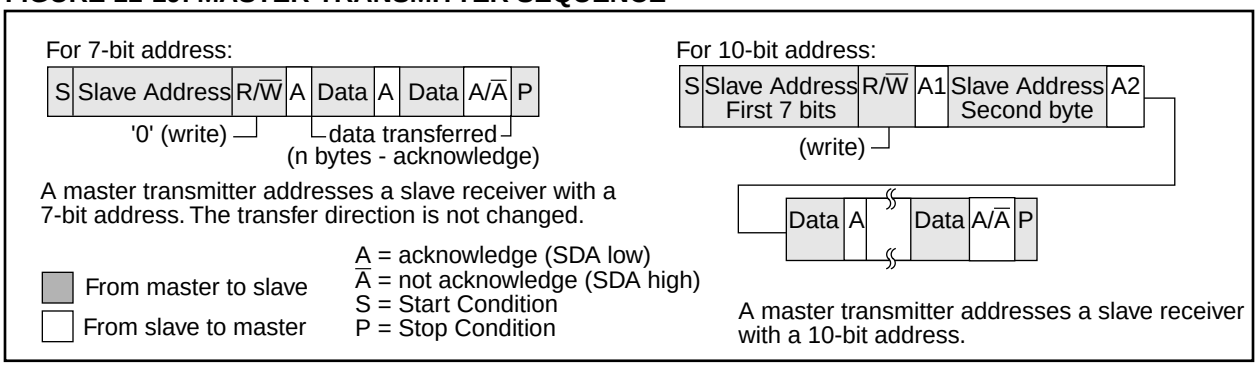


FIGURE 11-20: MASTER-RECEIVER SEQUENCE

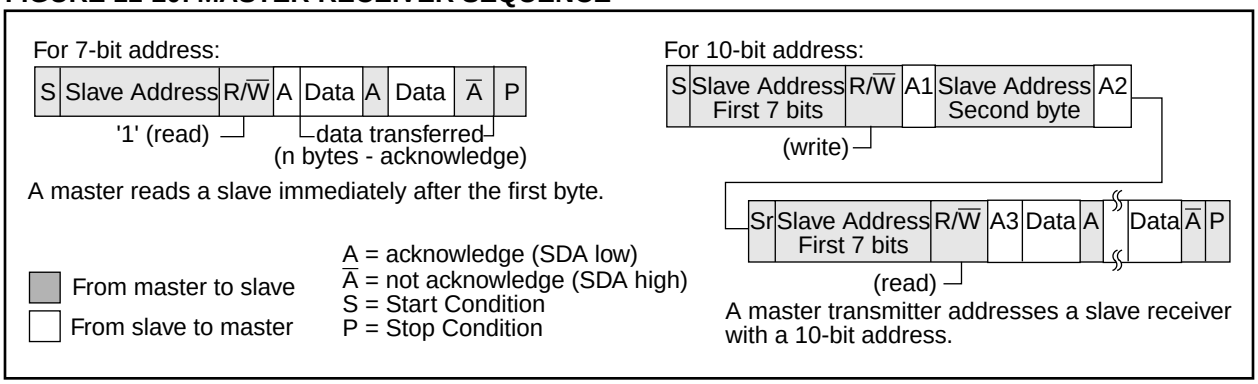
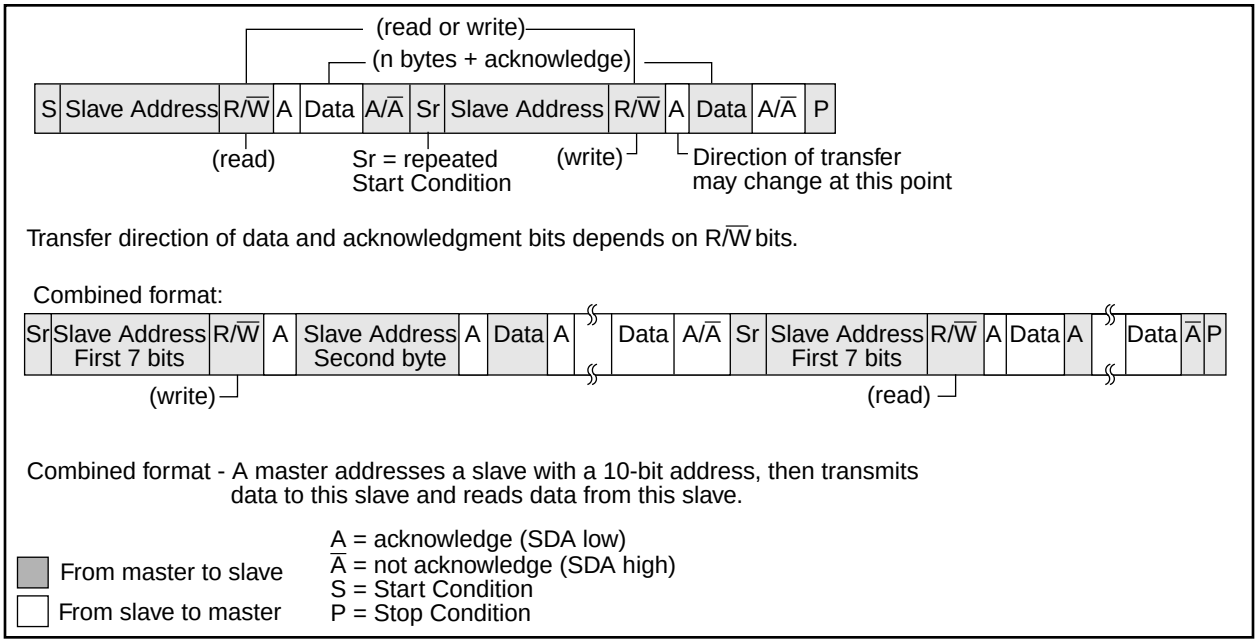


FIGURE 11-21: COMBINED FORMAT



12.1 USART Baud Rate Generator (BRG)

Applicable Devices						
72	73	73A	74	74A	76	77

The BRG supports both the Asynchronous and Synchronous modes of the USART. It is a dedicated 8-bit baud rate generator. The SPBRG register controls the period of a free running 8-bit timer. In asynchronous mode bit BRGH (TXSTA<2>) also controls the baud rate. In synchronous mode bit BRGH is ignored. Table 12-1 shows the formula for computation of the baud rate for different USART modes which only apply in master mode (internal clock).

Given the desired baud rate and Fosc, the nearest integer value for the SPBRG register can be calculated using the formula in Table 12-1. From this, the error in baud rate can be determined.

Example 12-1 shows the calculation of the baud rate error for the following conditions:

FOSC = 16 MHz
Desired Baud Rate = 9600
BRGH = 0
SYNC = 0

EXAMPLE 12-1: CALCULATING BAUD RATE ERROR

Desired Baud rate = Fosc / (64 (X + 1))

9600 = 16000000 /(64 (X + 1))

X = ⌊25.042⌋ = 25

Calculated Baud Rate=16000000 / (64 (25 + 1))

= 9615

$$\text{Error} = \frac{\text{(Calculated Baud Rate - Desired Baud Rate)}}{\text{Desired Baud Rate}}$$

= (9615 - 9600) / 9600

= 0.16%

It may be advantageous to use the high baud rate (BRGH = 1) even for slower baud clocks. This is because the FOSC/(16(X + 1)) equation can reduce the baud rate error in some cases.

Note:	For the PIC16C73/73A/74/74A, the asynchronous high speed mode (BRGH = 1) may experience a high rate of receive errors. It is recommended that BRGH = 0. If you desire a higher baud rate than BRGH = 0 can support, refer to the device errata for additional information, or use the PIC16C76/77.

Writing a new value to the SPBRG register, causes the BRG timer to be reset (or cleared), this ensures the BRG does not wait for a timer overflow before outputting the new baud rate.

TABLE 12-1: BAUD RATE FORMULA

SYNC	BRGH = 0 (Low Speed)	BRGH = 1 (High Speed)
0	(Asynchronous) Baud Rate = FOSC/(64(X+1))	Baud Rate= FOSC/(16(X+1))
1	(Synchronous) Baud Rate = FOSC/(4(X+1))	NA

X = value in SPBRG (0 to 255)

TABLE 12-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used by the BRG.

13.2 Selecting the A/D Conversion Clock

Applicable Devices						
72	73	73A	74	74A	76	77

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 9.5TAD per 8-bit conversion. The source of the A/D conversion clock is software selectable. The four possible options for TAD are:

- 2TOSC
- 8TOSC
- 32TOSC
- Internal RC oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of 1.6 µs.

Table 13-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

13.3 Configuring Analog Port Pins

Applicable Devices						
72	73	73A	74	74A	76	77

The ADCON1, TRISA, and TRISE registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS2:CHS0 bits and the TRIS bits.

Note 1: When reading the port register, all pins configured as analog input channels will read as cleared (a low level). Pins configured as digital inputs, will convert an analog input. Analog levels on a digitally configured input will not affect the conversion accuracy.

Note 2: Analog levels on any pin that is defined as a digital input (including the AN7:AN0 pins), may cause the input buffer to consume current that is out of the devices specification.

TABLE 13-1: TAD vs. DEVICE OPERATING FREQUENCIES

AD Clock Source (TAD)		Device Frequency			
Operation	**ADCS1:ADCS0**	**20 MHz**	**5 MHz**	**1.25 MHz**	**333.33 kHz**
2TOSC	00	100 ns(2)	400 ns(2)	1.6 µs	6 µs
8TOSC	01	400 ns(2)	1.6 µs	6.4 µs	24 µs(3)
32TOSC	10	1.6 µs	6.4 µs	25.6 µs(3)	96 µs(3)
RC(5)	11	2 - 6 µs(1,4)	2 - 6 µs(1,4)	2 - 6 µs(1,4)	2 - 6 µs(1)

Legend: Shaded cells are outside of recommended range.

Note 1: The RC source has a typical TAD time of 4 µs.

2: These values violate the minimum required TAD time.

3: For faster conversion times, the selection of another clock source is recommended.

4: When device frequency is greater than 1 MHz, the RC A/D conversion clock source is recommended for sleep operation only.

5: For extended voltage devices (LC), please refer to Electrical Specifications section.

13.4.1 FASTER CONVERSION - LOWER RESOLUTION TRADE-OFF

Not all applications require a result with 8-bits of resolution, but may instead require a faster conversion time. The A/D module allows users to make the trade-off of conversion speed to resolution. Regardless of the resolution required, the acquisition time is the same. To speed up the conversion, the clock source of the A/D module may be switched so that the TAD time violates the minimum specified time (see the applicable electrical specification). Once the TAD time violates the minimum specified time, all the following A/D result bits are not valid (see A/D Conversion Timing in the Electrical Specifications section.) The clock sources may only be switched between the three oscillator versions (cannot be switched from/to RC). The equation to determine the time before the oscillator can be switched is as follows:

Conversion time = $2T_{AD} + N \bullet T_{AD} + (8 - N)(2T_{OSC})$
Where: N = number of bits of resolution required.

Since the TAD is based from the device oscillator, the user must use some method (a timer, software loop, etc.) to determine when the A/D oscillator may be changed. Example 13-3 shows a comparison of time required for a conversion with 4-bits of resolution, versus the 8-bit resolution conversion. The example is for devices operating at 20 MHz and 16 MHz (The A/D clock is programmed for $32T_{OSC}$), and assumes that immediately after $6T_{AD}$, the A/D clock is programmed for $2T_{OSC}$.

The $2T_{OSC}$ violates the minimum TAD time since the last 4-bits will not be converted to correct values.

EXAMPLE 13-3: 4-BIT vs. 8-BIT CONVERSION TIMES

	Freq. (MHz)(1)	Resolution	
		4-bit	8-bit
TAD	20	1.6 µs	1.6 µs
	16	2.0 µs	2.0 µs
TOSC	20	50 ns	50 ns
	16	62.5 ns	62.5 ns
$2T_{AD} + N \bullet T_{AD} + (8 - N)(2T_{OSC})$	20	10 µs	16 µs
	16	12.5 µs	20 µs

Note 1: PIC16C7X devices have a minimum TAD time of 1.6 µs.

14.2 Oscillator Configurations

Applicable Devices						
72	73	73A	74	74A	76	77

14.2.1 OSCILLATOR TYPES

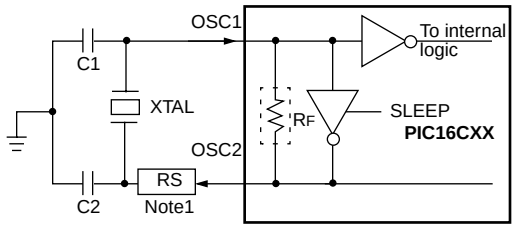
The PIC16CXX can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

14.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT, LP or HS modes a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 14-3). The PIC16CXX Oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1/CLKIN pin (Figure 14-4).

FIGURE 14-3: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



See Table 14-1 and Table 14-2 for recommended values of C1 and C2.

Note 1: A series resistor may be required for AT strip cut crystals.

FIGURE 14-4: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

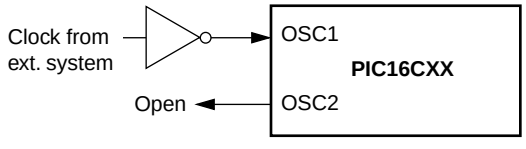


TABLE 14-1: CERAMIC RESONATORS

Ranges Tested:			
Mode	**Freq**	**OSC1**	**OSC2**
XT	455 kHz 2.0 MHz 4.0 MHz	68 - 100 pF 15 - 68 pF 15 - 68 pF	68 - 100 pF 15 - 68 pF 15 - 68 pF
HS	8.0 MHz 16.0 MHz	10 - 68 pF 10 - 22 pF	10 - 68 pF 10 - 22 pF
These values are for design guidance only. See notes at bottom of page.			
Resonators Used:			
455 kHz	Panasonic EFO-A455K04B	± 0.3%	
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%	
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%	
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%	
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%	
All resonators used did not have built-in capacitors.			

TABLE 14-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
These values are for design guidance only. See notes at bottom of page.			
Crystals Used			
32 kHz	Epson C-001R32.768K-A	± 20 PPM	
200 kHz	STD XTL 200.000KHz	± 20 PPM	
1 MHz	ECS ECS-10-13-1	± 50 PPM	
4 MHz	ECS ECS-40-20-1	± 50 PPM	
8 MHz	EPSON CA-301 8.000M-C	± 30 PPM	
20 MHz	EPSON CA-301 20.000M-C	± 30 PPM	

Note 1: Recommended values of C1 and C2 are identical to the ranges tested (Table 14-1).
2: Higher capacitance increases the stability of oscillator but also increases the start-up time.
3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
4: Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification.

TABLE 14-8: INITIALIZATION CONDITIONS FOR ALL REGISTERS (Cont.'d)

Register	Applicable Devices							Power-on Reset, Brown-out Reset	$\overline{MCLR}$ Resets WDT Reset	Wake-up via WDT or Interrupt
SSPADD	72	73	73A	74	74A	76	77	0000 0000	0000 0000	uuuu uuuu
SSPSTAT	72	73	73A	74	74A	76	77	--00 0000	--00 0000	--uu uuuu
TXSTA	72	73	73A	74	74A	76	77	0000 -010	0000 -010	uuuu -uuu
SPBRG	72	73	73A	74	74A	76	77	0000 0000	0000 0000	uuuu uuuu
ADCON1	72	73	73A	74	74A	76	77	---- -000	---- -000	---- -uuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition

Note 1: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

3: See Table 14-7 for reset value for specific condition.

14.5.1 INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered: either rising if bit INTEDG (OPTION<6>) is set, or falling, if the INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). Flag bit INTF must be cleared in software in the interrupt service routine before re-enabling this interrupt. The INT interrupt can wake-up the processor from SLEEP, if bit INTE was set prior to going into SLEEP. The status of global interrupt enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See Section 14.8 for details on SLEEP mode.

14.5.2 TMR0 INTERRUPT

An overflow (FFh → 00h) in the TMR0 register will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>). (Section 7.0)

14.5.3 PORTB INTCON CHANGE

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<4>). (Section 5.2)

Note:	For the PIC16C73/74, if a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

14.6 Context Saving During Interrupts

Applicable Devices						
72	73	73A	74	74A	76	77

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt i.e., W register and STATUS register. This will have to be implemented in software.

Example 14-1 stores and restores the STATUS, W, and PCLATH registers. The register, W_TEMP, must be defined in each bank and must be defined at the same offset from the bank base address (i.e., if W_TEMP is defined at 0x20 in bank 0, it must also be defined at 0xA0 in bank 1).

The example:

a) Stores the W register.
b) Stores the STATUS register in bank 0.
c) Stores the PCLATH register.
d) Executes the ISR code.
e) Restores the STATUS register (and bank select bit).
f) Restores the W and PCLATH registers.

EXAMPLE 14-1: SAVING STATUS, W, AND PCLATH REGISTERS IN RAM

```
MOVWF    W_TEMP           ;Copy W to TEMP register, could be bank one or zero
SWAPF    STATUS,W         ;Swap status to be saved into W
CLRF     STATUS           ;bank 0, regardless of current bank, Clears IRP,RP1,RP0
MOVWF    STATUS_TEMP      ;Save status to bank zero STATUS_TEMP register
MOVF     PCLATH, W        ;Only required if using pages 1, 2 and/or 3
MOVWF    PCLATH_TEMP      ;Save PCLATH into W
CLRF     PCLATH           ;Page zero, regardless of current page
BCF      STATUS, IRP      ;Return to Bank 0
MOVF     FSR, W           ;Copy FSR to W
MOVWF    FSR_TEMP         ;Copy FSR from W to FSR_TEMP
:
:(ISR)
:
MOVF     PCLATH_TEMP, W   ;Restore PCLATH
MOVWF    PCLATH           ;Move W into PCLATH
SWAPF    STATUS_TEMP,W    ;Swap STATUS_TEMP register into W
                          ;(sets bank to original state)
MOVWF    STATUS           ;Move W into STATUS register
SWAPF    W_TEMP,F         ;Swap W_TEMP
SWAPF    W_TEMP,W         ;Swap W_TEMP into W
```

CLRF **Clear f**

Syntax: [*label*] CLRF f

Operands: $0 \le f \le 127$

Operation: 00h → (f)
1 → Z

Status Affected: Z

Encoding:

00	0001	1fff	ffff

Description: The contents of register 'f' are cleared and the Z bit is set.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write register 'f'

Example
```
CLRF    FLAG_REG
```
Before Instruction
FLAG_REG = 0x5A
After Instruction
FLAG_REG = 0x00
Z = 1

CLRW **Clear W**

Syntax: [*label*] CLRW

Operands: None

Operation: 00h → (W)
1 → Z

Status Affected: Z

Encoding:

00	0001	0xxx	xxxx

Description: W register is cleared. Zero bit (Z) is set.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No-Operation	Process data	Write to W

Example
```
CLRW
```
Before Instruction
W = 0x5A
After Instruction
W = 0x00
Z = 1

CLRWDT **Clear Watchdog Timer**

Syntax: [*label*] CLRWDT

Operands: None

Operation: 00h → WDT
0 → WDT prescaler,
1 → $\overline{TO}$
1 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

00	0000	0110	0100

Description: CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No-Operation	Process data	Clear WDT Counter

Example
```
CLRWDT
```
Before Instruction
WDT counter = ?
After Instruction
WDT counter = 0x00
WDT prescaler = 0
$\overline{TO}$ = 1
$\overline{PD}$ = 1

Applicable Devices	72	73	73A	74	74A	76	77

17.2 DC Characteristics: PIC16LC72-04 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial				
Param No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	Supply Voltage	VDD	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
D010	Supply Current (Note 2,5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	µA	LP osc configuration FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D015*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	µA	BOR enabled VDD = 5.0V
D020	Power-down Current (Note 3,5)	IPD	-	7.5	30	µA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021			-	0.9	5	µA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	5	µA	VDD = 3.0V, WDT disabled, -40°C to +85°C
D023*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	µA	BOR enabled VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

Applicable Devices	72	73	73A	74	74A	76	77

18.5 Timing Diagrams and Specifications

FIGURE 18-2: EXTERNAL CLOCK TIMING

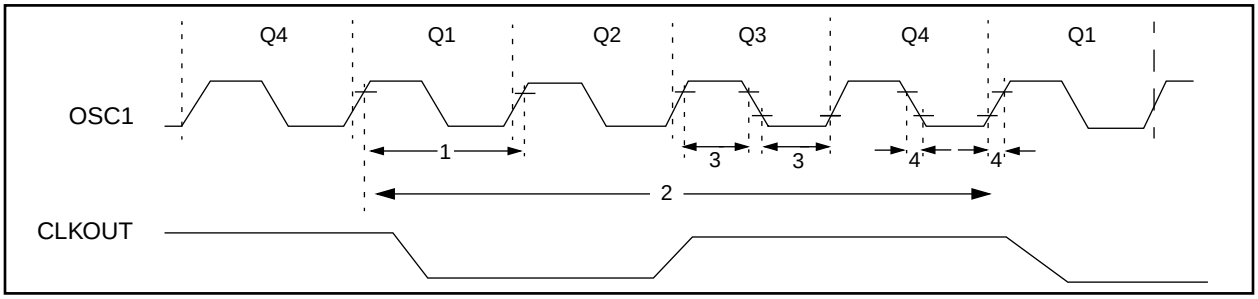


TABLE 18-2: EXTERNAL CLOCK TIMING REQUIREMENTS

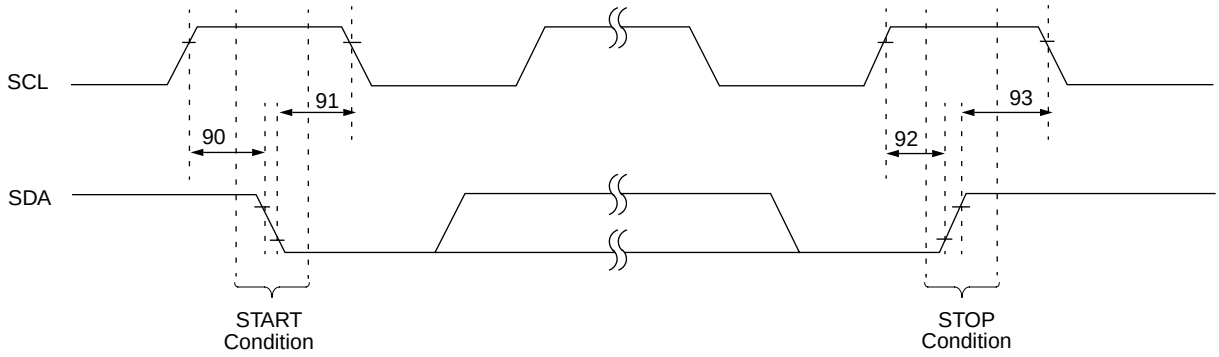
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	**External CLKIN Frequency (Note 1)**	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
1	Tosc	**External CLKIN Period (Note 1)**	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	µs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	µs	LP osc mode
2	TCY	**Instruction Cycle Time (Note 1)**	200	—	DC	ns	TCY = 4/FOSC
3	TosL, TosH	**External Clock in (OSC1) High or Low Time**	50	—	—	ns	XT oscillator
			2.5	—	—	µs	LP oscillator
			15	—	—	ns	HS oscillator
4	TosR, TosF	**External Clock in (OSC1) Rise or Fall Time**	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 18-9: I^2C BUS START/STOP BITS TIMING



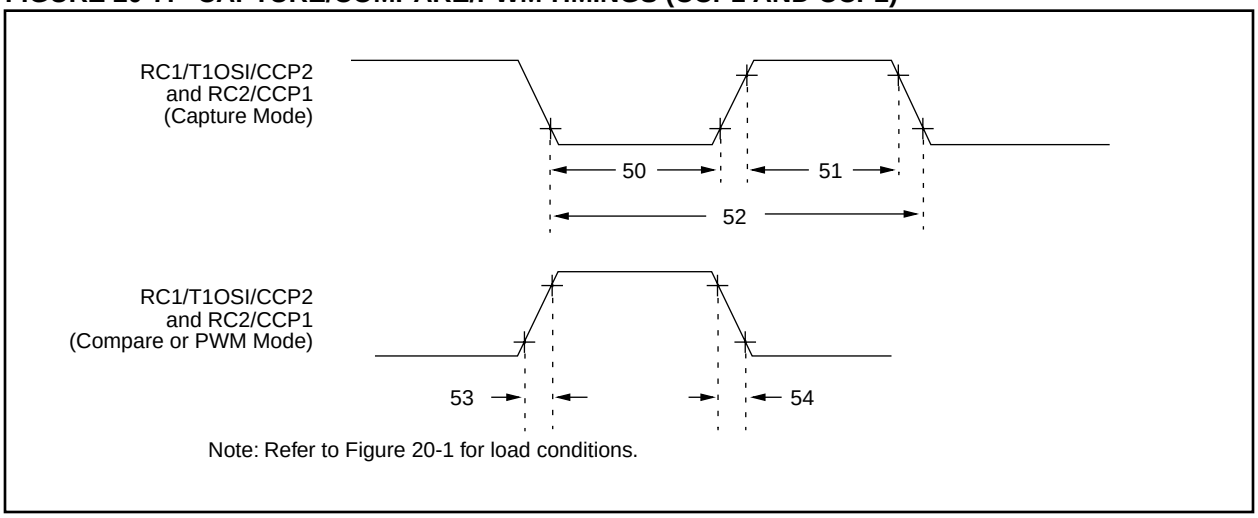
Note: Refer to Figure 18-1 for load conditions

TABLE 18-9: I^2C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ	Max	Units	Conditions
90	TSU:STA	START condition Setup time	100 kHz mode	4700	—	—	ns	Only relevant for repeated START condition
			400 kHz mode	600	—	—		
91	THD:STA	START condition Hold time	100 kHz mode	4000	—	—	ns	After this period the first clock pulse is generated
			400 kHz mode	600	—	—		
92	TSU:STO	STOP condition Setup time	100 kHz mode	4700	—	—	ns	
			400 kHz mode	600	—	—		
93	THD:STO	STOP condition Hold time	100 kHz mode	4000	—	—	ns	
			400 kHz mode	600	—	—		

Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 20-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)



Note: Refer to Figure 20-1 for load conditions.

TABLE 20-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)

Param No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2 input low time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	PIC16**C**76/77	10	—	—	ns	
				PIC16**LC**76/77	20	—	—	ns	
51*	TccH	CCP1 and CCP2 input high time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	PIC16**C**76/77	10	—	—	ns	
				PIC16**LC**76/77	20	—	—	ns	
52*	TccP	CCP1 and CCP2 input period			$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4 or 16)
53*	TccR	CCP1 and CCP2 output rise time		PIC16**C**76/77	—	10	25	ns	
				PIC16**LC**76/77	—	25	45	ns	
54*	TccF	CCP1 and CCP2 output fall time		PIC16**C**76/77	—	10	25	ns	
				PIC16**LC**76/77	—	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated.
These parameters are for design guidance only and are not tested.

Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 21-16: TYPICAL IDD vs. FREQUENCY (RC MODE @ 300 pF, 25°C)

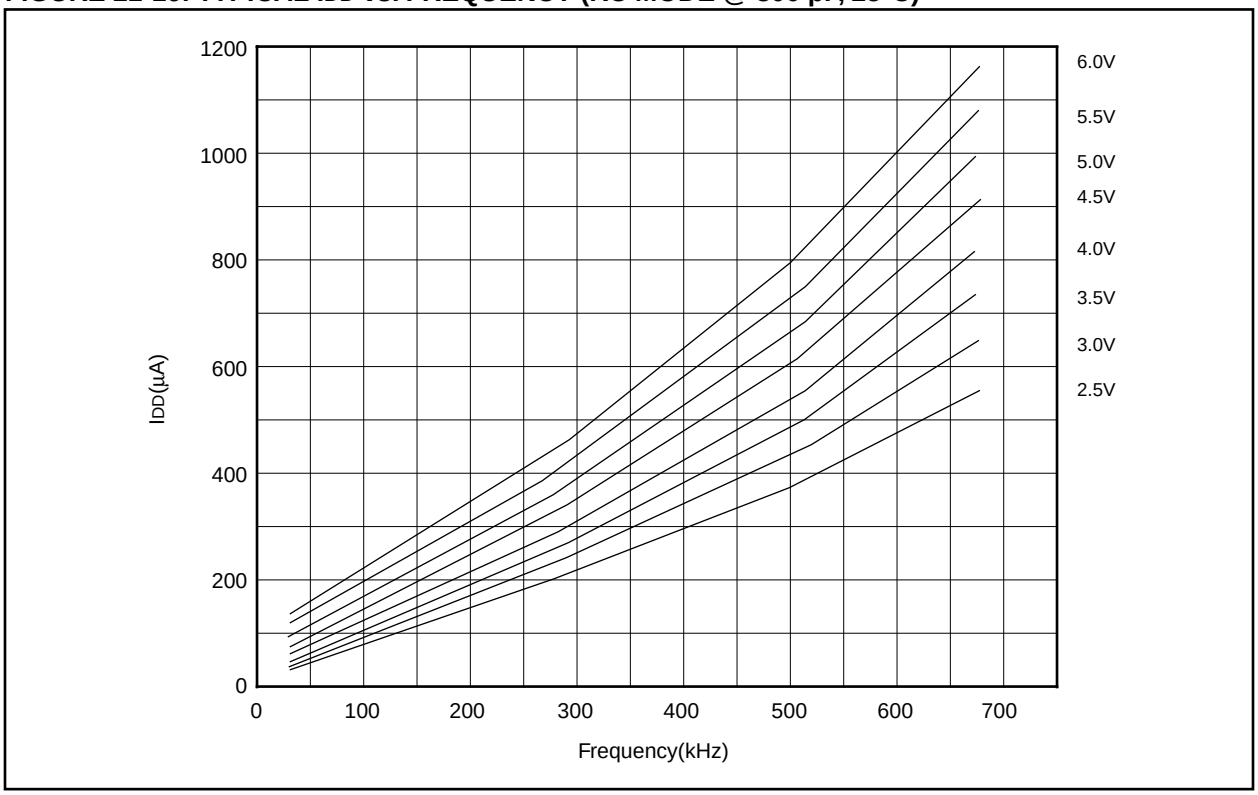
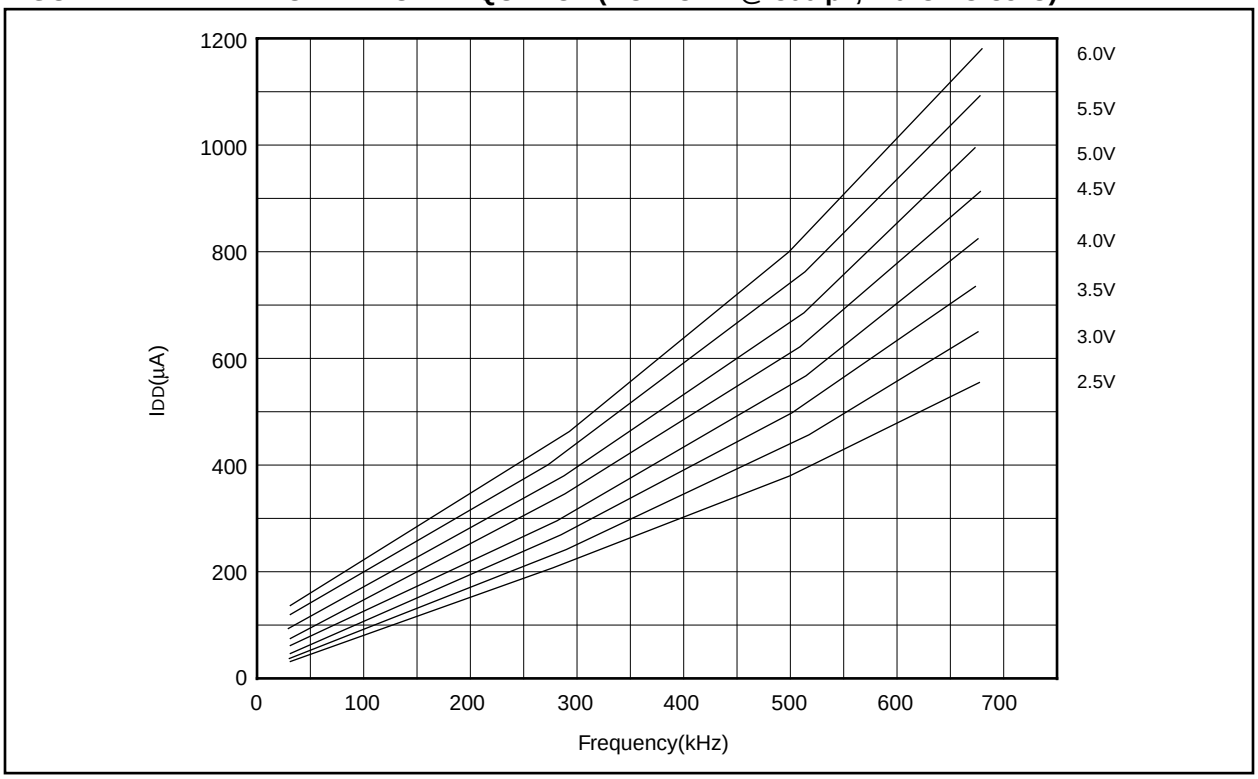
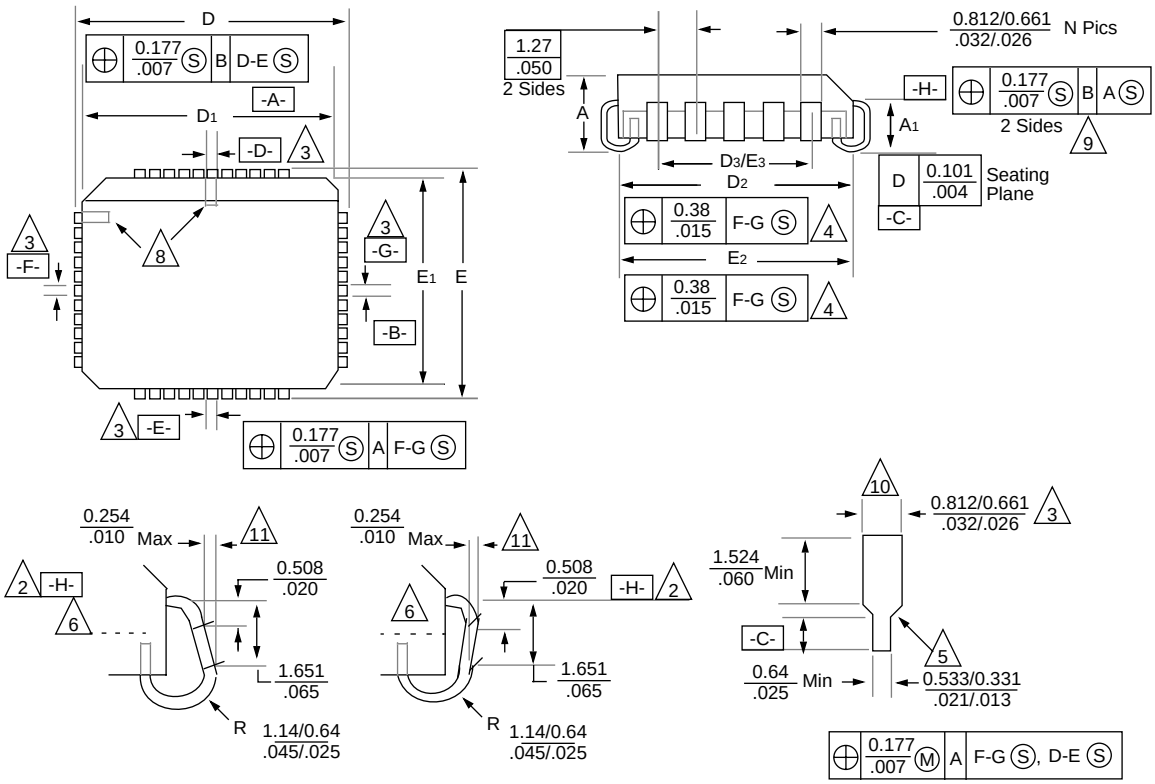


FIGURE 21-17: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 300 pF, -40°C TO 85°C)



Data based on matrix samples. See first page of this section for details.

22.7 44-Lead Plastic Leaded Chip Carrier (Square)(PLCC)



Package Group: Plastic Leaded Chip Carrier (PLCC)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
A	4.191	4.572		0.165	0.180	
A1	2.413	2.921		0.095	0.115	
D	17.399	17.653		0.685	0.695	
D1	16.510	16.663		0.650	0.656	
D2	15.494	16.002		0.610	0.630	
D3	12.700	12.700	**Reference**	0.500	0.500	**Reference**
E	17.399	17.653		0.685	0.695	
E1	16.510	16.663		0.650	0.656	
E2	15.494	16.002		0.610	0.630	
E3	12.700	12.700	**Reference**	0.500	0.500	**Reference**
N	44	44		44	44	
CP	–	0.102		–	0.004	
LT	0.203	0.381		0.008	0.015	

LIST OF FIGURES